



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D
<i>* : Required Field</i>			


Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2016-10-26
Contact Name *	Refer to Supplier Comment section		Refer to Supplier Comment section
Authorized Representative *	Rossana Bonaccorso	Representative Title	ADG MD Champion
Representative Phone *	Refer to Supplier Comment section	Representative Email *	Refer to Supplier Comment section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

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Legal Statement			
Supplier Acceptance *	true	Legal Declaration *	Standard
Legal Statement	<p>Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.</p>		

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
VNQ7040AYTR	RRVC*VH42BDW	A	MUAR B/E	2016-10-26
	Amount	UoM	Unit type	ST ECOPACK Grade
	488.00	mg	Each	ECOPACK2

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
3	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
NAC	Tin (Sn), matte	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
DSO	10.3-7.5-2.28	36	gull wing	
Comment	PwSSO36 DUAL CHIP			

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-April 2015	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	true
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	FALSE
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	false
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	FALSE
Exemption Id.	Description

QueryList : REACH-20th June 2016				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration : note : Substance present with less 0.001mg will not be declared in this document						Mfr Item Name	RRVC*VH42BDW					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Dies	Other inorganic materials	10.306	mg	supplier	die	Silicon (Si)	7440-21-3		9.877	mg	958374	20240
				supplier	metallization	Aluminium (Al)	7429-90-5		0.005	mg	485	10
				supplier	metallization	Copper (Cu)	7440-50-8		0.052	mg	5046	107
				supplier	metallization	Titanium (Ti)	7440-32-6		0.166	mg	16107	340
				supplier	Passivation	Silicon Nitride	12033-89-5		0.030	mg	2911	61
				supplier	Passivation	Silicon Oxide	7631-86-9		0.096	mg	9315	197
				supplier	back side metallization	Titanium (Ti)	7440-32-6		0.003	mg	291	6
				supplier	back side metallization	Gold (Au)	7440-57-5		0.009	mg	873	18
				supplier	back side metallization	Nickel (Ni)	7440-02-0		0.037	mg	3590	76
				supplier	back side metallization	Vanadium (V)	7440-62-2		0.003	mg	291	6
Leadframe	Copper & its alloys	225.944	mg	supplier	polymer die coating	PIX1 Gamma-butyrolactone	96-48-0		0.028	mg	2717	58
				supplier	alloy	Copper (Cu)	7440-50-8		218.161	mg	965553	447051
				supplier	alloy	Iron (Fe)	7439-89-6		5.131	mg	22709	10514
				supplier	alloy	Iron Phosphide (FeP)	26508-33-8		0.309	mg	1368	633
				supplier	alloy	Zinc (Zn)	7440-66-6		0.269	mg	1191	551
				supplier	metallization	Silver (Ag)	7440-22-4		2.074	mg	9179	4250
				supplier	glue or tape	Acrylic resin	9003-01-4		0.413	mg	630534	846
Die attach	Other Organic Materials	0.655	mg	supplier	glue or tape	epoxy resin	25068-38-6		0.242	mg	369466	496
				supplier	glue or tape	Lead (Pb)	7439-92-1		3.475	mg	974755	7121
Soft solder	Solder	3.565	mg	JIG - R	solder	Silver (Ag)	7440-22-4		0.054	mg	15147	111
				supplier	solder	Tin (Sn)	7440-31-5		0.036	mg	10098	74
				supplier	wire	Copper (Cu)	7440-50-8		2.334	mg	1000000	4783
Bonding wires	Other inorganic materials	2.334	mg	supplier	wire	Silica, vitreous	60676-86-0		208.031	mg	864002	426293
				supplier	mold compound	Epoxy Resin	25068-38-6		18.058	mg	74999	37004
				supplier	mold compound	Phenol Resin	29690-82-2		12.039	mg	50001	24670
				supplier	mold compound	3-Mercaptopropyl trimethoxysilane	4420-74-0		1.204	mg	5000	2467
				supplier	mold compound	Quartz	14808-60-7		0.722	mg	2999	1480
				supplier	mold compound	Carbon black	1333-86-4		0.722	mg	2999	1480
Connections coating	Solder	4.420	mg	supplier	solder alloy	Tin (Sn)	7440-31-5		4.420	mg	1000000	9057